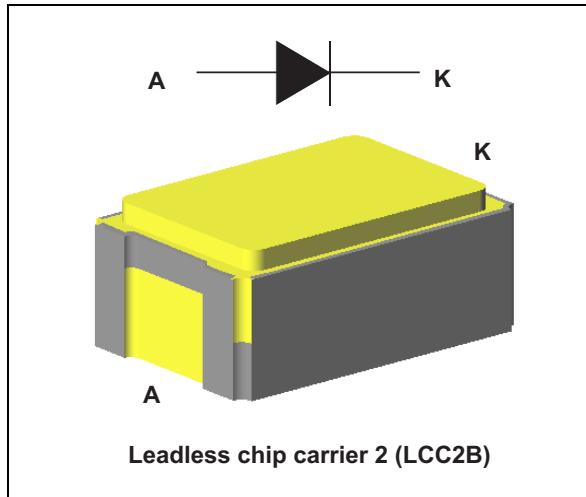


Aerospace 40 V power Schottky rectifier

Datasheet - production data



Description

This power Schottky rectifier is designed and packaged to comply with the ESCC5000 specification for aerospace products. It is housed in a surface mount hermetically sealed LCC2B package whose footprint is 100% compatible with industry standard solutions in D5B.

The 1N5822U is suitable for switching mode power supplies and high frequency DC to DC converters such as low voltage high frequency inverter, free wheeling or polarity protection.

Features

- Aerospace applications
- Surface mount hermetic package
- High thermal conductivity materials
- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop
- Package mass: 0.18 g
- Target radiation qualification
 - 150 krad (Si) low dose rate
 - 3 Mrad (Si) high dose rate
- ESCC qualified

Table 1. Device summary⁽¹⁾

Order code	ESCC detailed specification	Quality level	Lead finish	EPPL	$I_{F(AV)}$	V_{RRM}	$T_{j(max)}$	$V_{F(max)}$
1N5822UB1		Engineering model	Gold		3	40	150	0.485
1N5822U01B	5106/020/01	ESCC	Gold	yes				
1N5822U02B	5106/020/02	ESCC	Solder dip	yes				

1. Contact ST sales office for information about the specific conditions for products in die form.

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	40	V
$I_{F(RMS)}$	Forward rms current	10	A
$I_{F(AV)}$	Average forward rectified current	$T_c \geq 139\text{ }^\circ\text{C}, \bar{\delta} = 0.5$	A
I_{FSM}	Forward surge current	$t_p = 10\text{ ms sinusoidal}$	A
T_{stg}	Storage temperature range	-65 to +150	$^\circ\text{C}$
T_j	Maximum operating junction temperature ⁽¹⁾	150	$^\circ\text{C}$
T_{sol}	Maximum soldering temperature ⁽²⁾	245	$^\circ\text{C}$

- $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink
- Maximum duration 5 s. The same package must not be re-soldered until 3 minutes have elapsed.

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	7	$^\circ\text{C/W}$

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit	
I_R ⁽¹⁾	Reverse current	$T_j = -55\text{ }^\circ\text{C}$	$V_R = 40\text{ V}$	-	-	40	μA
		$T_j = 25\text{ }^\circ\text{C}$		-	-	80	
		$T_j = 100\text{ }^\circ\text{C}$		-	-	12	mA
V_F ⁽²⁾	Forward voltage	$T_j = 25\text{ }^\circ\text{C}$	$I_F = 1\text{ A}$	-	-	0.4	V
		$T_j = -55\text{ }^\circ\text{C}$	$I_F = 3\text{ A}$	-	-	0.56	
		$T_j = 25\text{ }^\circ\text{C}$		-	-	0.485	
		$T_j = 100\text{ }^\circ\text{C}$		-	-	0.455	
		$T_j = 25\text{ }^\circ\text{C}$	$I_F = 9.4\text{ A}$	-	-	0.70	

- Pulse test: $t_p = 5\text{ ms}, \bar{\delta} < 2\%$
- Pulse test: $t_p = 680\text{ }\mu\text{s}, \bar{\delta} < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.32 \times I_{F(AV)} + 0.050 \times I_{F(RMS)}^2$$

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_j	Diode capacitance	$V_R = 5\text{ V}, F = 1\text{ MHz}$	-	-	240	pF

Figure 1. Average forward power dissipation versus average forward current

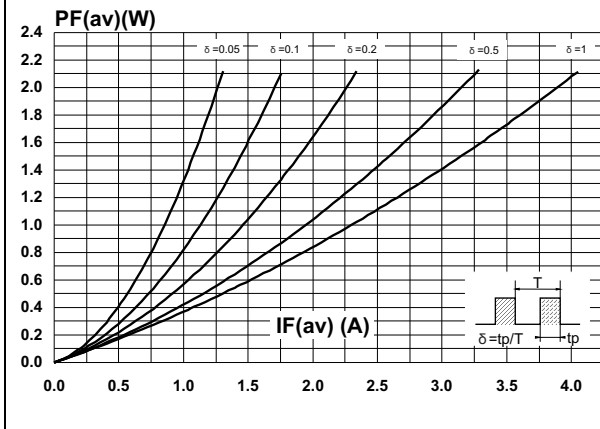


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

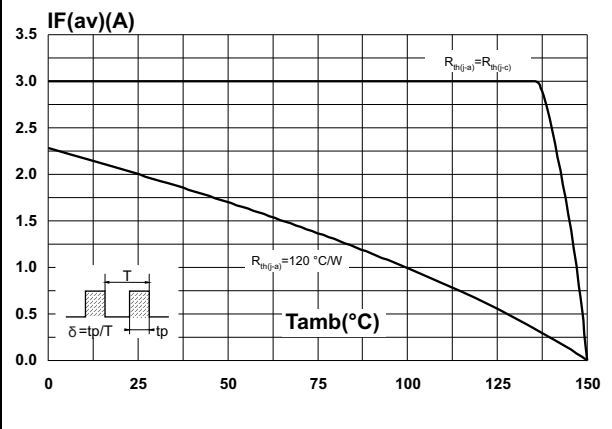


Figure 3. Non repetitive surge peak forward current versus overload duration (maximum values)

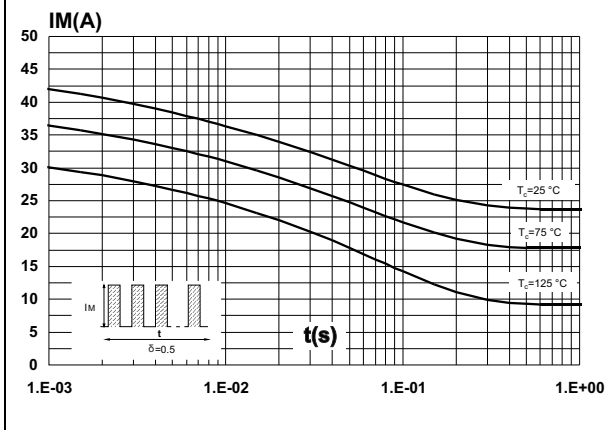


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

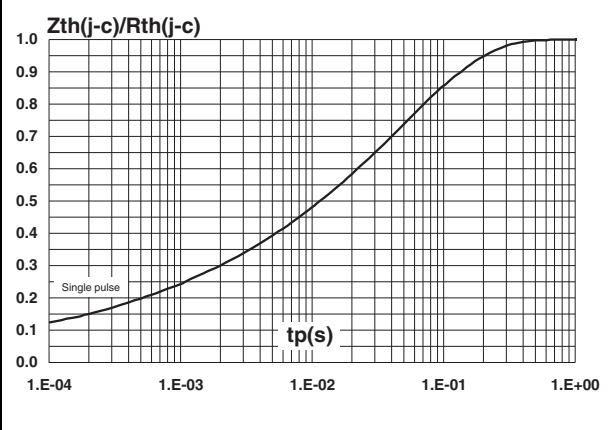


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

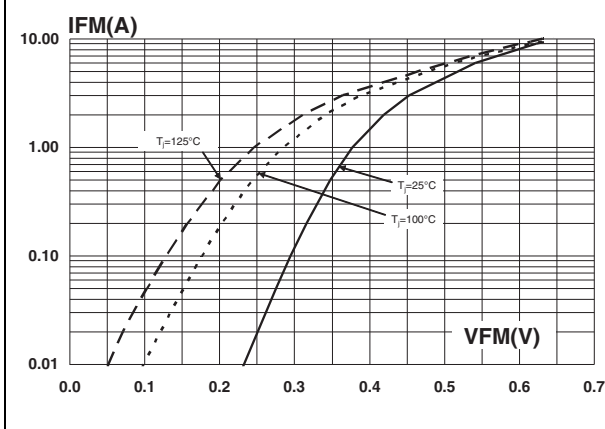


Figure 6. Forward voltage drop versus forward current (typical values)

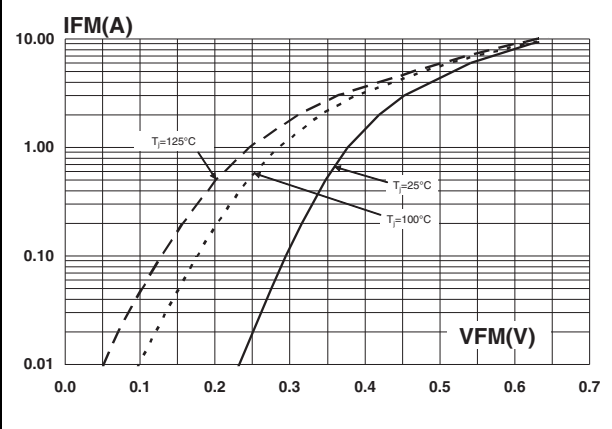
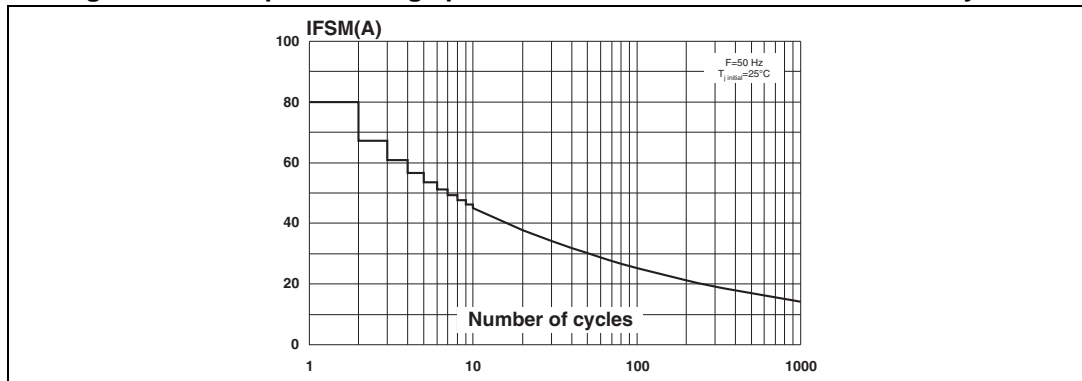


Figure 7. Non repetitive surge peak forward current versus number of cycles

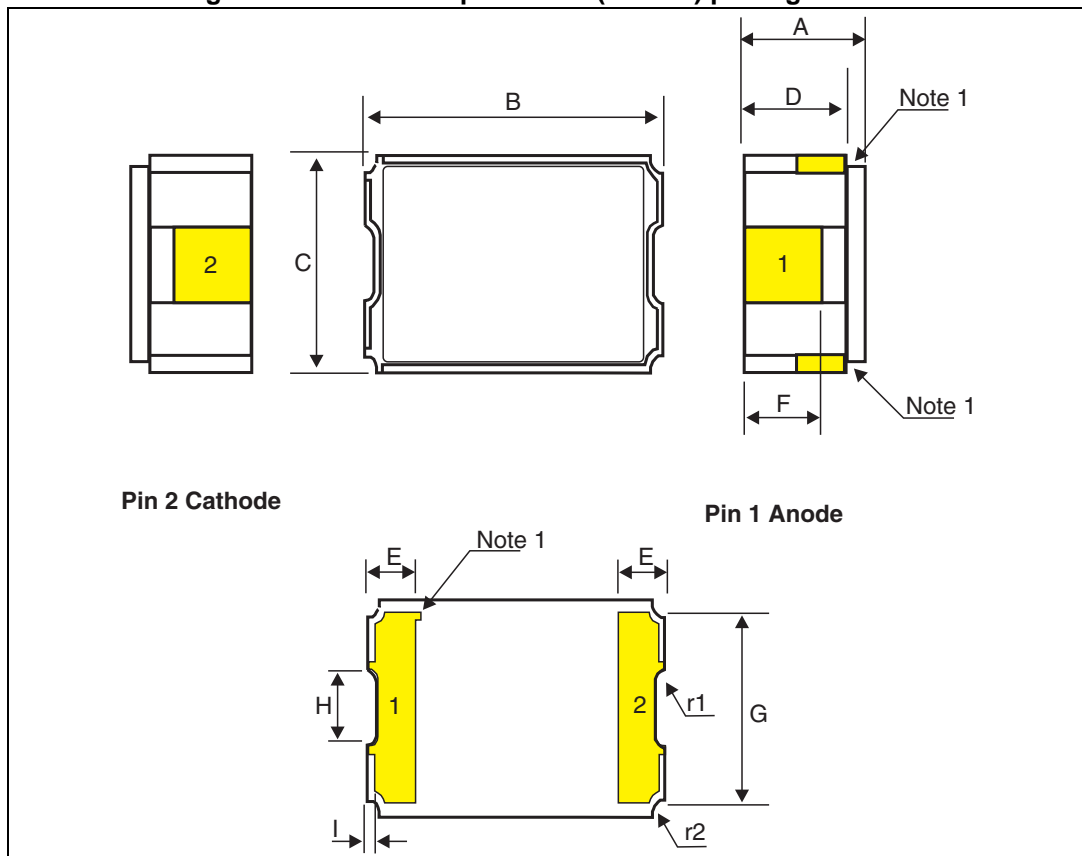


2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 Leadless chip carrier 2 (LCC2B) package information

Figure 8. Leadless chip carrier 2 (LCC2B) package outline



1. The anode is identified by metalization in two top internal angles and the index mark.

Table 6. Leadless chip carrier 2 (LCC2B) package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A ⁽¹⁾	2.04	2.23	2.42	0.080	0.088	0.095
B	5.27	5.4	5.6	0.207	0.213	0.220
C	3.49	3.62	3.76	0.137	0.143	0.148
D	1.71	1.90	2.09	0.067	0.075	0.082
E	0.48	-	0.71	0.019	-	0.028
F	-	1.4	-	-	0.055	-
G	-	3.32	-	-	0.131	-
H	-	1.82	-	-	0.072	-
I	-	0.15	-	-	0.006	-
r1	-	0.15	-	-	0.006	-
r2	-	0.20	-	-	0.008	-

1. Measurement prior to solder coating the mounting pads on bottom of package

3 Ordering information

Table 7. Ordering information⁽¹⁾

Order code	ESCC detailed specification	Package	Lead finish	Marking ⁽²⁾	EPPL	Mass	Packing
1N5822UB1		LCC2B	Gold	1N5822UB1	-	0.18 g	Waffle pack
1N5822U01B	5106/020/01		Gold	510602001	Y		
1N5822U02B	5106/020/02		Solder dip	510602002	Y		

1. Contact ST sales office for information about the specific conditions for products in die form.

2. Specific marking only. The full marking includes in addition:

For the engineering models: ST logo, date code, country of origin (FR).

For ESCC flight parts: ST logo, date code, country of origin (FR), ESA logo, serial number of the part within the assembly lot.

4 Other information

4.1 Date code

Date code is structured as describe below:

- EM xyywwz
- ESCC flight yywwz

Where:

- x (EM only): 3, assembly location Rennes (France)
- yy: last two digits year
- ww: week digits
- z: lot index in the week

4.2 Documentation

In [Table 8](#) is a summary of the documentation provided with each type of products.

Table 8. Documentation provided with each type of products

Quality level	Documentation
Engineering model	
ESCC flight	Certificate of conformance

5 Revision history

Table 9. Document revision history

Date	Revision	Changes
10-Aug-2009	1	First issue.
25-Sep-2011	2	Updated ESCC status in Features and added footnote to Table 3.
8-Nov-2013	3	Updated Table 1, Table 2, Table 5 and Table 7 and inserted Other information.
08-Dec-2015	4	Updated Table 7 and reformatted to current standard.

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